

AMENDMENTS TO THE CLAIMS

Claims 4, 5 and 7 are pending in this application. Claims 4 and 5 are herein amended.

The listing of claims will replace all prior versions, and listings, of claims in the application.

Listing of Claims

1-3. (Canceled)

4. (Currently Amended) A method of producing an assembly comprising a printed-circuit electronics card mounted on a metal substrate with a metal screening cover electrically connected to the metal substrate, the method comprising:

forming a gutter on a the ~~metallie~~ substrate by stamping;

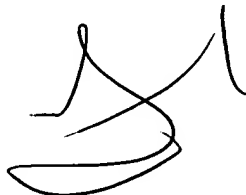
mounting a the printed circuit electronics card onto a surface of the ~~metallie~~ substrate adjacent to the gutter;

positioning a the metal screening cover having an edge including a tab so that the tab rests substantially within the gutter; and

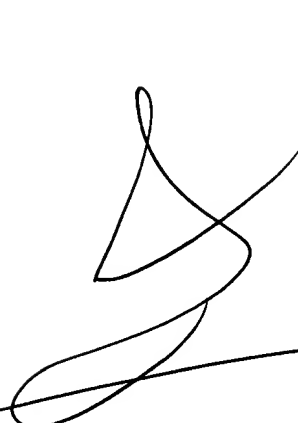
crimping the ~~metallie~~ substrate to secure the tab of the metal screening cover onto the metal substrate, ~~whereby wherein~~ the metal screening cover ~~may be~~ is positioned to electromagnetically screen the printed circuit electronics card.

5. (Currently Amended) A method according to claim 4, wherein the crimping is carried out by localized crushing of a portion of the metal substrate over the tab.

6. (Canceled)



7. (Previously Amended) A method according to claim 4, wherein the tab comprises a plurality of tabs, wherein more than one tab is crimped.

 Concluded